Program: CMS-4MOD3 or CMS-6MOD2

Part Orientation:

1. Pitch Adapter to Silicon Bonds

Lead Reference System (L): Pitch Adapter

Die Reference System (U): Silicon

First Bond: Pitch Adapter
Bond time: 20 ms
USG Current: 60 to 75mA
Force: 20

Second Bond: Silicon
Bond time: 20 ms
USG Current: 45 to 55mA
Force: 35

Loop Parameters:
Shape: square
Loop height: 45 mils
Clear height: 55 mils
clamp close at loop

Tail Parameters:
Feed: 75
2. Silicon to Silicon Bonds

**Lead Reference System (L): Left Silicon wafer**

First Bond: Left Silicon wafer
Bond time: 20 ms  
USG Current: 45 to 50mA  
Force: 35  

Loop Parameters:
- Shape: square  
- Loop height: 45 mils  
- Clear height: 55 mils  
- Clamp close at loop

**Die Reference System (U): Right Silicon wafer**

Second Bond: Right Silicon wafer
Bond time: 20 ms  
USG Current: 45 to 55mA  
Force: 35  

Tail Parameters:
- Feed: 75
3. Bias Bonds

Bond Locations:

Pitch Adapter to Silicon:

First Bond: Pitch Adapter
Bond time: 20ms
USG Current: 60 to 75mA
Force: 20

Second Bond: Silicon
Bond time: 20 ms
USG Current: 45 to 50mA
Force: 35

Loop Parameters:
Shape: square
Loop height: 35 mils
Clamp close at loop

Tail Parameters:
Feed: 75

Silicon to Silicon:

First Bond: Left Silicon wafer
Bond time: 20 ms
USG Current: 45 to 55mA
Force: 35

Second Bond: Right Silicon wafer
Bond time: 20 ms
USG Current: 45 to 55mA
Force: 35
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<thead>
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<th><strong>Loop Parameters:</strong></th>
<th><strong>Tail Parameters:</strong></th>
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<tbody>
<tr>
<td>Shape: square</td>
<td>Feed: 75</td>
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